

# Republic of the Philippines



INTELLECTUAL PROPERTY  
P H I L I P P I N E S  
BUREAU OF PATENTS

Patent No. 1-2011-500063

Having complied with the provisions of Republic Act No. 8293 and its regulations, this Office grants **LETTERS PATENT** for an

## INVENTION

the pertinent data, specification and claim/s of which are hereunto annexed and made part hereof.

Now, therefore, this **LETTERS PATENT** grants unto its owner/s the exclusive right throughout the Philippines to make, use, sell or import the invention and where the invention is or includes a process, including the product obtained directly or indirectly from such process; and,

Unless sooner terminated as provided for by law and the regulations, the term of this **LETTERS PATENT** shall be **TWENTY (20) YEARS** from the date of filing.

IN WITNESS WHEREOF, I have hereunto affixed my hand and the seal of the Intellectual Property Office at Taguig City, Philippines



  
**EPIFANIO M. EVASCO**  
Director of Patents

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[1] Title: SUPPLY MECHANISM FOR THE CHUCK OF AN INTEGRATED CIRCUIT DICING DEVICE

[71] Applicant(s): ROKKO SYSTEMS PTE, LTD., [SINGAPORE]

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[30] Foreign Application Priority Data: SG 2004 05166-0 23/08/2004 SG; SG 2005 01802-3 22/03/2005 SG and SG 2005 05056-2 15/07/2005 SG

[51] Int. Class<sup>8</sup>: H 01L 21/00, 21/304, 21/673, 21/677, 21/78

[58] Field of search: H 01L 21/00, 21/304, 21/673, 21/677, 21/78

[56] Reference(s) Considered/Cited:

Category	Document description	Relevant to claim No.	Document No.
X	US 7,829,383 B2 - HAE CHOON YANG 9 November 2010		1
A	US 6,196,532 B1 - OTWELL March 2001		2

[57] **ABSTRACT**

A system for dicing substrates to singulate integrated circuit units within in them includes a dicing machine (Z) which operates with a chuck table (4). A lifting assembly (Ax,Ay) deposits substrates to be singulated onto the chuck table (4) at substantially the same time as it removes previously singulated units from the chuck table (4).

Industry / Technical Field	Electrical and Electronics			
No. of Claim(s)	5	claim/s	Drawing(s)	24 sheet/s
Multiple Dep. Claim(s)	0	claim/s	Specification and Claim(s)	30 page(s)
Specie/s Claim(s)	0	claim/s	Sequence Listings	0 page(s)
Total No. of Claim(s)	5	claim/s		

Examiner: Leodelino C. Paden

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